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			·	TRANSPORTER							
Examiner Initial		Document Number	Date	Name		Class	Subclass	Filing If Appr			
In	AA	6,063,701	05/16/00	Kuwazaki et al.							
	AB	5,899,737	05/04/99	Trabucco		_					
	AC	5,763,854	06/09/98	Dittman et al.		-					
	AD	5,762,258	06/09/98	Le Coz et al.	•	_					
	AE	5,495,089	02/27/96	Freedman et al.			=				
$\sqrt{}$	AF	5,431,332	07/11/95	Kirby et al.							
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		от	HER REFERE	NCES (including Author, Title, Date,	Pertinent Pages, Etc.)						
MT	AR	Kasulke et al., Solder Ball Bumper (SBB) - A Flexible Equipment for FC, CSP, BGA and Printed Circuit Boards/An Innovative Solution for,									
		Solder Application Solder Ball Bumper (SBB), Pac Tech Packaging Technologies GmbH and Fraunhoser IZM, pp. 1-8.									
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		•	U.S. PATENT DOCUMENTS	3						
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AR	Kasulke, P., et a	on for Solder B	all Bumper (SBB) - A Flexible r Application Solder Ball Bumpe	Equipment for FC, C r (SBB)*, Pac Tech	Packaging T	rechnologies	GmbH and	3 , An		
 	Praunhofer 12M	See 1DS filed 11/2/9E, Paper No. 3								
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